1. SCOPE

This specification covers standards on tape packaging and related practices for NEC Electronics subminiature electron device '8PIN HWSON'.

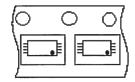
2. ORDERING INFORMATION AND DEVICE ORIENTATION

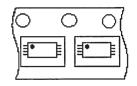


Device orientation (as shown below) Type No.

← Reel side

Leader side \rightarrow





ORIENTATION "E1" ORIENTATION "E2"

3. SPECIFICATION

3. 1 TAPE DIMENSIONS Fig. 1

3. 2 DIMENSIONS ON REEL Fig. 2

······· Table1 3. 3 LEADER AND TRAILER

3. 4 RELATED PRACTICES

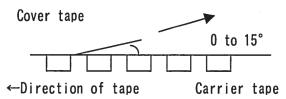
3. 4. 1 MISSING DEVICE

ITEM	SPEC	REMARKS
Successive void	None	Except leader or trailer portion
Non-successive void	O. 2%MAX. /reel	Except leader or trailer portion

3. 4. 2 MECHANICAL DATA

ITEM	Reference DATA	REMARKS
Cover tape adhesion	0. 4±0. 3N	As shown below

F ($S=300\pm10$ mm/min.)



3. 4. 3 TAKING DEVICES OUT OF THE TAPE

- (1) Devices should not adhere to the cover tape.
- (2) Flush of epoxy resin should not affect on taking out the devices.

3. 4. 4 SPLICING

No carrier or cover tape should be spliced, within 1 reel.

3. 4. 5 ELECTRICAL CHARACTERISTICS

Electrical characteristics of taping device shall be provided in the specification.

3. 4. 6 KEEPING CONDITIONS

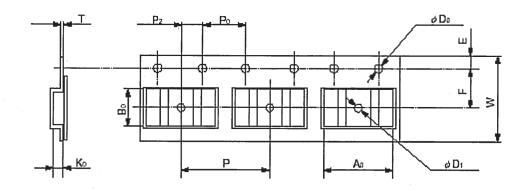
Maximum Temperature: 40℃

Maximum Humidity: 80%

4. QUANTITY

3,000 pieces/reel

Fig. 1 TAPE DIMENSIONS

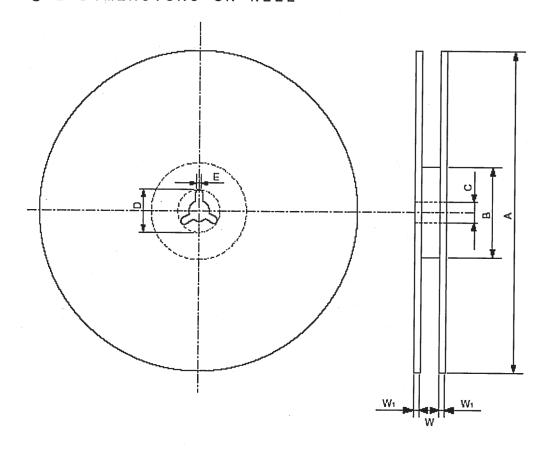


⇒ Direction of feed

Symbol	Specification	
Αo	7. OMAX.	
Во	3. 7MAX.	
Κο	1. 7	
W	12±0.3	
F	5. 5±0. 1	
E	1. 75±0. 1	
Р	8. 0±0. 1	
P ₂	2. 0±0. 1	
Po	4. 0±0. 1	
D ₀	1. 55±0. 05	
Т	0. 3	
D ₁	1. 5MIN.	

(Unit; mm)

Fig. 2 DIMENSIONS ON REEL



Symbol	Specification	
Α	Ф330±2. 0	
В	Ф100	
С	Ф13±0. 2	
D	Ф21±0.8	
E	2. 0±0. 5	
W	13. 4	
W ₁	2. 0±0. 5	

(Unit; mm)

Table 1 LEADER AND TRAILER

	ITEM	SPECIFICATION	REMARKS
Leader	Cover tape	Cover tape without carrier 200mm MIN.	Tip taped to roll
	Carrier tape	100mm MIN.	
		Total 400mm MIN.	
Trailer		160mm MIN.	Without hub slit part